

FORM PTO-1449  
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U.S. Application Serial No.  
10/796,602

Atty. Docket No.  
AM-2044.C2



INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT

(Use several sheets if necessary)

Tony Chiang et al.  
Applicants

March 8, 2004  
Filing Date

1745  
Group

U. S. PATENT DOCUMENTS

Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
<u>AK</u>	4,407,712	10/04/83	Henshaw et al.	204	298	
	4,514,437	04/30/85	Nath	427	39	
	4,657,778*	04/14/87	Moran	427	53.1	
	4,792,842**	12/20/88	Honma et al.	357	71	
	4,944,961	07/31/90	Lu et al.	427	38	
	4,976,839	12/11/90	Inoue	204	192.17	
	5,186,718	02/16/93	Tepman et al.	29	25.01	
	5,236,868	08/17/93	Nulman	437	190	
	5,246,885	09/21/93	Braren et al.	437	225	
	5,281,854**	01/25/94	Wong	257	740	
<u>Ac</u>	5,302,266**	04/12/94	Grabarz et al.	204	192.12	

Examiner AK Date Considered 9/4/04

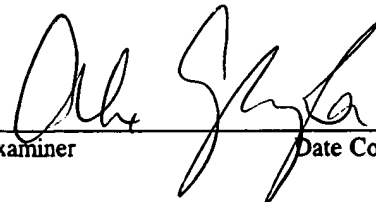
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\* Cited by the Examiner in parent application, U.S. Serial No. 09/886,439, and/or grandparent application, U.S. Serial No. 08/978,792.

\*\* Cited on Search Report in corresponding PCT Application No. PCT/US98/22796.

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Examiner Initial	Document Number	Issue Date	Name	Class	Subclass	Filing Date If Appropriate
AC	5,312,509	05/17/94	Eschbach	156	345	
	5,320,728	06/14/94	Tepman	204	192.12	
	5,354,712	10/11/94	Ho et al.	437	195	
	5,358,616	10/25/94	Ward	204	192.15	
	5,478,455	12/26/95	Actor et al.	204	192.13	
	5,520,784	05/28/96	Ward	204	192.15	
	5,585,673	12/17/96	Joshi et al.	257	751	
	5,589,713**	12/31/96	Lee et al.	257	773	
	5,658,438*	08/19/97	Givens et al.	204	192.11	
	5,723,367**	03/03/98	Wada et al.	437	248	02/20/96
	5,725,739*	03/10/98	Hu	204	192.3	07/08/96
	5,780,357	07/14/98	Xu et al.	438	639	06/02/97
	5,783,282*	07/21/98	Leiphart	428	138	10/07/96
	5,897,752*	04/27/99	Hong et al.	204	192.12	05/20/97
	5,962,923	10/05/99	Xu et al.	257	774	08/07/95
AC	6,605,197	08/12/03	dING ET AL.	204	192.15	05/13/97


9/4/04  
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# FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Publication Date	Name	Class	Subclass	Translation If Appropriate
AC	EP 0451571**	10/16/91	Wang	H01L	21/3205	
AC	EP 0823279	11/02/98	Aitchison	B01D	53/46	
AC	JP 8097279**	12/04/96	Shima et al.	H01L	021/768	

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

AC	Rossnagel et al., "Metal ion deposition from ionized magnetron sputtering discharge", <i>J. Vac. Sci. Technol. B</i> , Vol. 12, No. 1, pp. 449 - 453 (Jan/Feb 1994).
AC	Rossnagel et al., "Thin, high atomic weight refractory film deposition for diffusion barrier, adhesion layer, and seed layer applications", <i>J. Vac. Sci. Technol. B</i> , Vol. 14, No. 3, pp. 1819 - 1827 (May/Jun 1996)..

Examiner

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